

### 6N138 6N139

#### Features:

- High isolation voltage between input and output (Viso=5000 Vrms)
- Guaranteed performance from 0°C to 70°C
- Pb free and RoHS compliant.







### **Description**

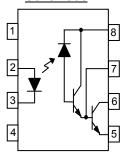
The 6N138 and 6N139 devices each consists of an infrared emitting diodes, optically coupled to a high gain split Darlington photo detectors.

They are packaged in an 8-pin DIP package and available in wide-lead spacing and SMD options.

### **Applications**

- Digital logic ground isolation
- RS-232C line receiver
- High common mode noise line receiver
- Microprocessor bus isolation
- Current loop receiver

#### Schematic



### 6N138/6N139

#### Pin Configuration

- 1. No Connection
- 2. Anode
- 3. Cathode
- 4. No Connection
- 5. Gnd
- 6. Vout
- $7. V_B$
- 8. Vcc

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### Absolute Maximum Ratings (Ta=25°C unless otherwise specified)

	Parameter		Symbol	Rating	Unit
	Forward current	I <sub>F</sub>	20	mA	
	Peak forward current (50% duty, 1ms P.W)		I <sub>FP</sub>	40	mA
Input	Peak transient current (≤1 μs P.W, 300pps)		I <sub>Ftrans</sub>	1	А
	Reverse voltage	dissipation P <sub>IN</sub> 35 r	V		
	Power dissipation		P <sub>IN</sub>	35	mW
	Power dissipation		Po	100	mW
	Output current		Io	1 A 5 V 35 mW 100 mW 60 mA 0.5 V -0.5 to 7 V -0.5 to 18 V -0.5 to 18 V	
	Emitter-Base Reverse Voltage		VER	0.5	V
Output	Outout valta sa	6N138	.,	-0.5 to 7	V
	Output voltage	6N139	Vo	-0.5 to 18	V
		6N138		-0.5 to 7	V
	Supply voltage	6N139	V <sub>CC</sub>	-0.5 to 18	V
Isolation	voltage *1		V <sub>ISO</sub>	5000	V rms
Operatin	g temperature		T <sub>OPR</sub>	-55 ~ +85	°C
Storage t	temperature		T <sub>STG</sub>	-55 ~ +125	°C
Soldering	g temperature *2		T <sub>SOL</sub>	260	°C

#### **Notes**

<sup>\*1</sup> AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2, 3, 4 are shorted together, and pins 5, 6, 7, 8 are shorted together.

<sup>\*2</sup> For 10 seconds.



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### Electrical Characteristics (T<sub>a</sub>=0 to 70°C unless specified otherwise) Input

Parameter	Symbol	Min.	Typ.*	Max.	Unit	Condition
Forward voltage	V <sub>F</sub>	-	1.3	1.7	V	I <sub>F</sub> = 1.6mA
Reverse Voltage	$V_R$	5.0	-	-	V	I <sub>R</sub> = 10μA, TA=25°C
Temperature coefficient of forward voltage	$\Delta V_F / \Delta T_A$	-	-1.8	-	mV/°C	I <sub>F</sub> =1.6mA

### Output

Parameter		Symbol	Min.	Тур.*	Max.	Unit	Condition
Logic High	6N139	ı	-	-	100	μΑ	
Output Current	6N138	ГОН	-	-	250		I <sub>F</sub> =0mA, V <sub>O</sub> =V <sub>CC</sub> =18V
Logic Low Supply Current	6N138 6N139	I <sub>CCL</sub>	1	-	1.5	mA	I <sub>F</sub> =1.6mA, V <sub>O</sub> =Open, V <sub>CC</sub> =18V
Logic High Supply Current	6N138 6N139	I <sub>CCH</sub>	-	-	10	μA	I <sub>F</sub> =0mA, V <sub>O</sub> =Open, V <sub>CC</sub> =18V

### Transfer Characteristics (T<sub>a</sub>=0 to 70°C unless specified otherwise, Vcc=4.5V)

Parameter		Symbol	Min.	Typ.*	Max.	Unit	Condition				
Current Transfer Ratio	6N139	6N139		400	ı	ı		$I_F = 0.5 \text{mA}, V_O = 0.4 \text{V},$ $V_{CC} = 4.5 \text{V}$			
		CTR	500	1	1	%	$I_F = 1.6 \text{mA}, V_O = 0.4 \text{V},$				
	6N138	1	300	ı	ı		V <sub>CC</sub> =4.5V				
							1	-	0.4		$I_F = 0.5 \text{mA}, I_O = 2 \text{mA},$ $V_{CC} = 4.5 \text{V}$
			-	-	0.4	V	$I_F = 1.6 \text{mA}, I_O = 8 \text{mA}, V_{CC} = 4.5 \text{V}$				
Logic Low Output Voltage	6N139	V <sub>OL</sub>	-	-	0.4		I <sub>F</sub> = 5mA, I <sub>O</sub> = 15mA, V <sub>CC</sub> =4.5V				
			ı	ı	0.4		$I_F = 12mA, I_O = 24mA, V_{CC} = 4.5V$				
	6N138		ı	ı	0.4		I <sub>F</sub> = 1.6mA, I <sub>O</sub> = 4.8mA, V <sub>CC</sub> =4.5V				

<sup>\*</sup> Typical values at T<sub>a</sub> = 25°C



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### Switching Characteristics (T<sub>a</sub>=0 to 70°C unless specified otherwise, Vcc=5V)

Parameter		Symbol	Min.	Typ.*	Max.	Unit	Condition
			-	-	25		$I_F$ = 0.5mA , $R_L$ =4.7k $\Omega$ , $T_A$ =25°C
			-	-	30		$I_F = 0.5 \text{mA}$ , $R_L = 4.7 \text{k}\Omega$
Propagation Delay Time to	6N139	TPHL	-	ı	1	μs	$I_F$ = 12mA , $R_L$ =270 $\Omega$ , $T_A$ =25°C
Logic Low			-	-	2	<b>,</b>	I <sub>F</sub> = 12mA , R <sub>L</sub> =270Ω
			-	-	10		$I_F$ = 1.6mA , $R_L$ =2.2k $\Omega$ , $T_A$ =25°C
	6N138		-	-	15		$I_F$ = 1.6mA , $R_L$ =2.2k $\Omega$
	6N139		-	-	60	μs	$I_F$ = 0.5mA , $R_L$ =4.7k $\Omega$ , $T_A$ =25°C
		TPLH	-	-	90		$I_F$ = 0.5mA , $R_L$ =4.7k $\Omega$
Propagation			-	ı	7		$I_F$ = 12mA , $R_L$ =270 $\Omega$ , $T_A$ =25°C
Delay Time to Logic High			-	-	10		$I_F$ = 12mA , $R_L$ =270 $\Omega$
			-	-	35		$I_F$ = 1.6mA , $R_L$ =2.2k $Ω$ , $T_A$ =25°C
	6N138		-	-	50		$I_F$ = 1.6mA , $R_L$ =2.2kΩ
Common Mode T Immunity at Logic		СМн	1,000	-	-	V/µs	$I_F$ = 0mA , $V_{CM}$ =10 $V_P$ - $p$ , $R_L$ =2.2 $K\Omega$ , $T_A$ =25 $^{\circ}C$
Common Mode Transient Immunity at Logic Low		CM <sub>L</sub>	1,000	-	-	V/µs	$I_F$ = 1.6mA , $V_{CM}$ =10 $V_P$ - $p$ , $R_L$ =2.2 $K\Omega$ , $T_A$ =25 $^{\circ}C$

<sup>\*</sup> Typical values at T<sub>a</sub> = 25°C



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### **Typical Performance Curves**

Fig.1 LED Forward Current vs. Forward Voltage

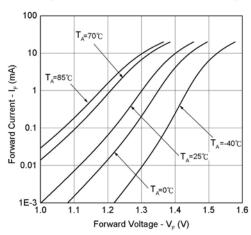
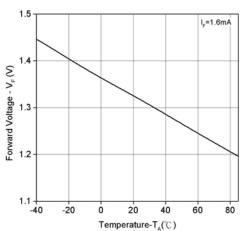
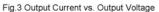


Fig.2 LED Forward Voltage vs. Temperature





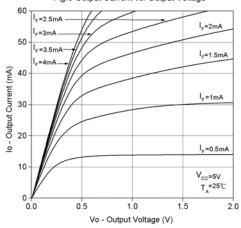
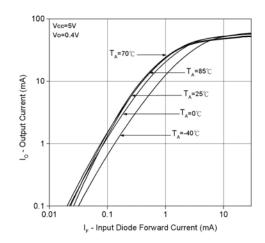


Fig.4 Output Current vs. Input Diode Forward Current





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Fig.5 Current Transfer Ratio vs. Forward Current

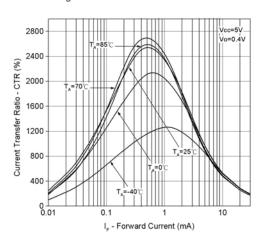


Fig.6 Current Transfer Ratio vs. Base-Emitter Resistance

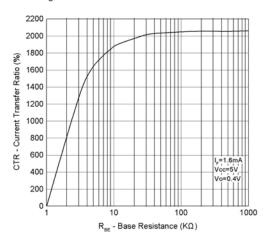


Fig.7 Non-saturated Rise nand Fall Times vs. Load Resistance

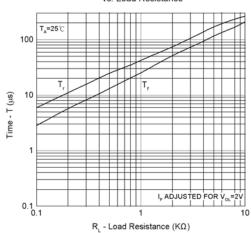
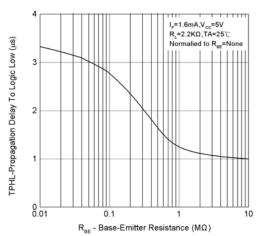


Fig.8 Propagation Delay To Logic Low vs. Base-Emitter Resistance





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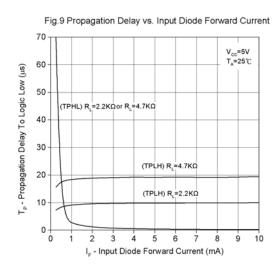


Fig. 10 Propagation Delay to Logic Low vs. Pulse Period

100

100

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I<sub>c</sub>=0.5mA

R<sub>c</sub>=4.7KΩ

1 I<sub>c</sub>=1.6mA

R<sub>c</sub>=2.2kΩ

1 I<sub>c</sub>=1.6mA

R<sub>c</sub>=2.2kΩ

1 I<sub>c</sub>=1.6mA

R<sub>c</sub>=2.2kΩ

1 I<sub>c</sub>=1.6mA

R<sub>c</sub>=2.2kΩ

Fig.11 Propagation Delay vs. Temperature

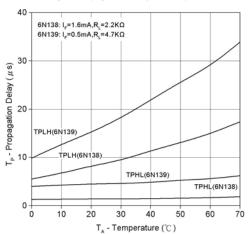
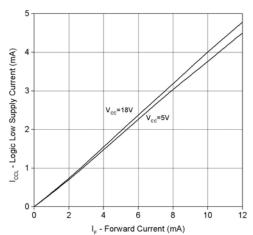


Fig.12 Logic Low Supply Current vs. Input Diode Forward Current





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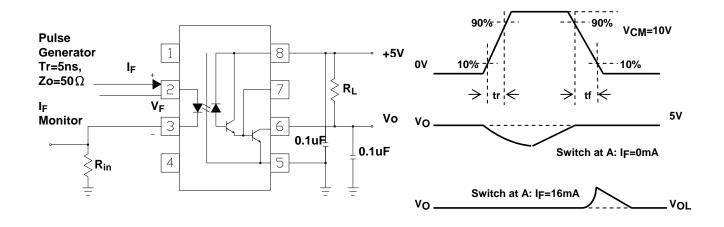


Fig. 13 Switching Time Test Circuit

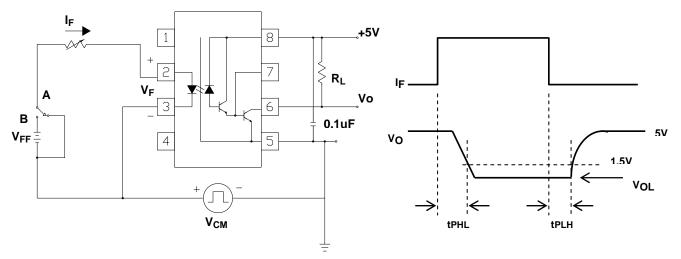


Fig. 14 Common Mode Transient Immunity Test Circuit



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**Order Information** 

**Part Number** 

**6N13XY** 

Note

Χ

= Part No. (X = 8 or 9) = Lead form option (G SM T+R or none)

Option	Description	Packing quantity
None	Standard DIP-8	45 units per tube
G	Wide lead bend (0.4 inch spacing)	45 units per tube
SM	Surface mount lead form	45 units per tube
SM T+R	Surface mount lead form + tape & reel	1000 units per reel

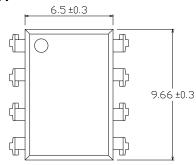


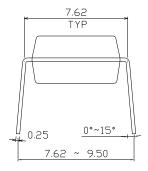
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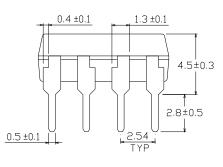
### **Package Drawing**

(Dimensions in mm)

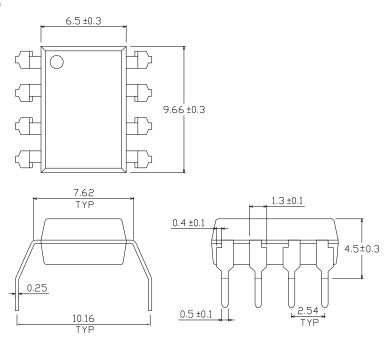
### **Standard DIP Type**







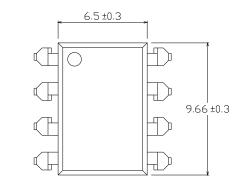
### **Option G Type**

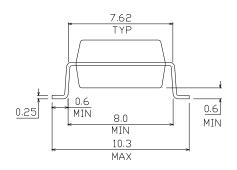


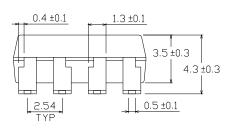


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### **Option SM Type**



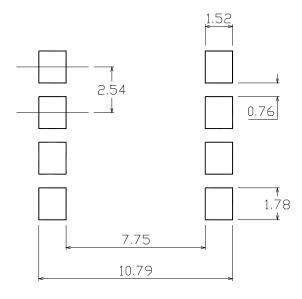




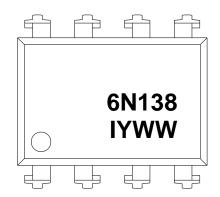


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### Recommended pad layout for surface mount leadform



### **Device Marking**



### **Notes**

6N138 denotes Device Number
Y denotes 1 digit Year code
WW denotes 2 digit Week code

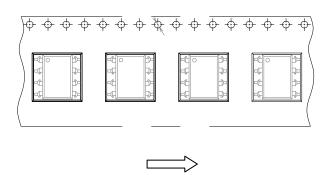
l denotes Isocom



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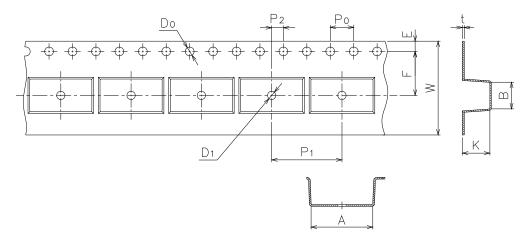
### **Tape & Reel Packing Specifications**

### **Option TA**



Direction of feed from reel

### **Tape dimensions**

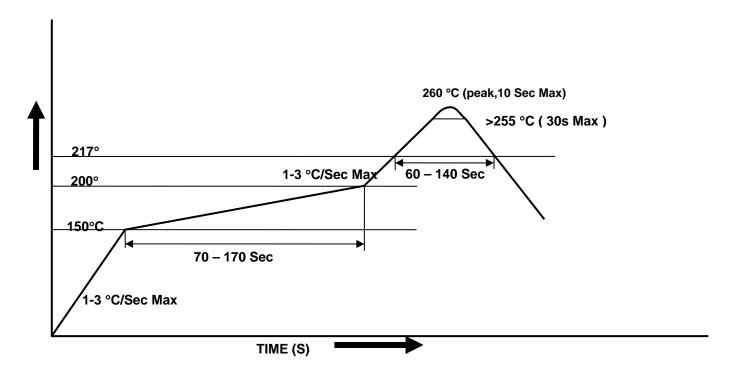


Dimension No.	Α	В	Do	D1	E	F
Dimension(mm)	10.4±0.1	10.0±0.1	1.5±0.1	1.5±0.1	1.75±0.1	7.5±0.1
Dimension No.	Ро	P1	P2	t	w	К



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### **Solder Reflow Temperature Profile**





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